	BLE STAN				Storage				
	Operating Temperature Range 2 Voltage Current				Temperatur	e Range	-10 °C to 60 °C (2)		(2)
Rating			Power Contact : 200 V AC		Storage Hur			midity 85% max	
			Signal Contact : 0.5 A Power Contact : 3.0A			perating Humidity Range (Not dewed)			
			SPEC	IFICATIO	ONS				
IT	EM		TEST METHOD			REQU	IREMENTS	QT	А
CONSTRU	JCTION								1
General Examination		Visually and by measuring instrument.			Accord	According to drawing.			>
Marking		Confirmed	-					×)
ELECTRIC CHARAC									
Contact Resistance		100 mA(DC or 1000Hz)			-	Signal Contact : $70m \Omega$ MAX. Power Contact : $20m \Omega$ MAX.			-
Insulation Resistance		Signal Contact : 100 V DC. Power Contact : 250 V DC			-	Signal Contact : 100 MΩMIN. Power Contact : 1000 MΩMIN.			-
Voltage Proof		Signal Contact : 150 V AC for 1 min.			Nie flee	No flashover or breakdown.			;
		Power Contact : 600 V AC for 1 min.			ino fias				-
MECHANI	ICAL CHAF								
Insertion and		Measured by applicable connector.				Insertion Force: 45 N MAX.			-
Withdrawal Forces						Withdrawal Force: 5 N MIN.			_
Mechanical Operation		100 times insertions and extractions.			S	 Contact Resistance: Signal Contact : 80m Ω MAX. Power Contact : 30m Ω MAX. No damage, crack and looseness of parts. 			_
Vibration		Frequency 10 to 55 to 10Hz, approx 5min Single amplitude : 0.75 mm, 10 cycles			① No	 No electrical discontinuity of 1 μs. No damage, crack and looseness of parts. 			-
Shock		for 3 axial directions. 490 m/s ² , duration of pulse 11 ms						×	-
			or 3 both axial directions.						
	MENTAL C			00.1				×	1
Damp Heat (Steady state)		Exposed at 40±2 °C, 90 ~ 95 %, 96 h.			S	 ① Contact Resistance: Signal Contact : 80m Ω MAX. 			-
Rapid Change of Temperature		Temperature-55 \rightarrow +85 °CTime30 \rightarrow 30 min.			_	Power Contact : 30m Ω MAX. ② Insulation Resistance:			-
remperature	•	under 5			-	Signal Contact			
		(Relocation time to chamber : within 2~3 MIN)			F	Power Contact			
Cold		Exposed at -55°C, 96 h			1 Cor	(1) Contact Resistance: Signal Contact : $80m \Omega$ MAX.			-
Dry Heat		Exposed at 105°C, 96 h			P	Power Contact : 30m Ω MAX. ② No damage, crack and looseness of parts.			-
Sulfur Dioxide		Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h.			. ① No	① No defect such as corrosion which impairs			† -
		(Test stand	(Test standard: IEC 68)			 the function of connector. (2) Contact Resistance: Signal Contact : 80m Ω MAX. Power Contact : 30m Ω MAX. 			
Resistance to		1)Reflow soldering :				No deformation of case of excessive			-
Soldering Heat		Peak TM	Peak TMP : 260°CMAX Reflow TMP: 220°CMIN for 60sec			looseness of the terminal.			
		2) Soldering irons : 360°C MAX. for 5 sec.							
Solderability			solder temperature or immersion duration, 3 se	ec.		ım of 95 % of	ng of solder shall cover a the surface being	×	-
COUN			N OF REVISIONS		SIGNED		CHECKED	<u>۸</u>	TE
2 2					S. 00N0				
-			00002065		3. UUNU			17.02.0	
⁽²⁾ "STORAGE" means a long-term storage state for the unused product before assembly to PCB.						HS. OKAWA Kn. shibuya	14.06.2		
						DESIGNED	TS. 00N0	14.06.2	
Unless otherwise specified, refer to IEC 60512.						DRAWN TS. 00N0			6.2
Note QT:Q		st AT:Assurance Test X:Applicable Test				DRAWING NO. ELC-353562-)
HRS		SPECIFICATION SHEET HIROSE ELECTRIC CO., LTD.					X23-100S-0.5SV10	~	4/
					DDE NO.	DE NO. CL573-3305-5-00			1/